On Semiconductor Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product-Env	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company unique ID Unique ID Authority Di Semiconductor Contact Name Title - Contact Title - Contact Product-Env-Stewards Product Enviro Compliance Title - Representative Title - Representative Title - Representative Title - Representative Phone - Representative* Phone - Representative* Product-Env-Stewards NA Product-Env-Stewards Onsemicon Namufacturing Site Weight* UOM Version Manufacturing Site Weight* Version Manufact	752-21.1										ials and Mf	g Informat	ion		
In Semiconductor In Semicondu	upplier Informa	ation								,					
Title - Contact Name Product Env-Stewards Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards © onsemi.com Nanufacturing Site Weight* UOM Nanufacturing Proccess Information Product Env-Stewards © onsemi.com Nanufacturing Site Nanufacturi	Company name* Company uniqu				ique ID U			Unique ID Authority				Response Date*			
Product-Env-Stewards	n Semiconductor											2021-02-03			
Authorized Representative* Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Number FDG6303N SC88 25V DUAL N-FET 450 MO 2021-02-03 Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed Title - Representative Product-Enviro Compliance NA Product-Env-Stewards Weight* UOM U CN1 5.759 mg I Manufacturing Site Weight* UOM I SC88 25V DUAL N-FET 450 MO 2021-02-03 Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM UMANUFER UOM UMANUFER	Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	ntative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Requester Item Number	Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date Version Manufacturing Si		Ianufacturing Site	V	Veight*	UOM	Unit Type	
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vel 1 - maximum time at beak temberature during soldering is 10-30 seconds				1	10 1										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	led					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recruired by the					
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.148	mg	Supplier	Silicon (Si)	7440-21-3		0.148	mg
Lead Frame	2.087		В	Nickel (Ni)	7440-02-0		0.7576	mg
			Supplier	Iron (Fe)	7439-89-6		1.0477	mg
			Supplier	Copper (Cu)	7440-50-8		0.2817	mg
Mold Compound-Black	3.224		Supplier	Boron zinc hydroxide oxide	138265-88-0		0.0967	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.0161	mg
			Supplier	2,4,6-triamino-1,3,5-triazine isocyanuric acid	37640-57-6		0.0967	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.418	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0161	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.4836	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0967	mg
Plating	0.274	mg	Supplier	Tin (Sn)	7440-31-5		0.274	mg
Wire Bond - Au	0.026	mg	Supplier	Gold (Au)	7440-57-5		0.026	mg